

### REMARKS

Claims 22-26 have been newly added. Support for claim 22 may be found on page 4, line 8. Support for claim 23 may be found on page 5, line 6. Support for claim 24 may be found on page 5, lines 25-26. Support for claim 25 may be found on page 9, lines 3-5 and the examples. Support for claim 26 may be found e.g., in originally filed claims 2-5. No new matter has been added. Entry is requested.

Claims 1-3, 8, 10, 12 and 13 are rejected under 35 U.S.C. § 102 (b) as being anticipated by Mehaffy et al. (EP 0934990A1).

Claim 5 is rejected under 35 U.S.C. 102 (b) as anticipated by or, in the alternative, under 35 U.S.C. § 103 (a) as being obvious over Mehaffy et al.

Claims 4 and 9 are rejected under 35 U.S.C. § 103 (a) as being unpatentable over Mehaffy et al.

Applicants note that the disclosure of Mehaffy et al. (EP 0934990A1) corresponds to U.S. Patent No. 6, 117,947.

Mehaffy is cited as disclosing a low application temperature adhesive that is applied at or below 200°F and wherein the bonded adhesive heat stress value and the adhesive application temperature are separated by 100°F or less. The examiner refers to paragraph 0033 and to Table I. Applicants disagree.

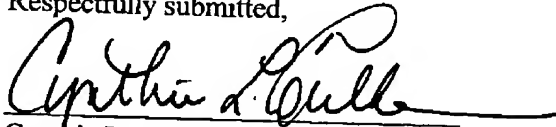
The adhesives presented in the examples of Mehaffy were applied at temperatures of 121°C, or at 249°F. The difference in the application temperature and the heat stress values reported in Table 1 range from 124°F to 134°F, i.e., these values are separated by more than

110°F as required in applicants' claim 1. Mehaffy neither anticipates nor renders obvious applicants' claimed invention. Withdrawal of the Section 102 and 103 rejections based on Mehaffy is requested

Claims 6 and 7 are rejected under 35 U.S.C. § 103 (a) as being unpatentable over Mehaffy et al. in view of Baetzold et al. (U.S. 5,827,913). The disclosure of Baetzold adds nothing to the disclosure of Mehaffy which would motivate the skilled artisan to formulate an adhesive that can be applied at a low temperature and which are able to withstand stress at temperatures substantially closer to the temperature of the adhesive's application temperature than heretofore achieved in the art. Withdrawal of the Section rejection based on Mehaffy in view of Baetzold is requested.

Applicants submit that the claimed invention represents an important and patentable contribution to the art. Favorable action is requested.

Respectfully submitted,



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July 25, 2006

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